

---

**Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections - Part 1: Plastic moulded enclosure outlines (IEC 61837-1:1999)**

Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections -- Part 1: Plastic moulded enclosure outlines

Oberflächenmontierbare piezoelektrische Bauteile zur Frequenzstabilisierung und - Selektion - Norm-Gehäusemaße und Anschlüsse -- Teil 1: Kunststoffgehäuse

Dispositifs piézoélectriques à montage en surface pour la commande et le choix de la fréquence - Encombrements normalisés et connexions des sorties -- Partie 1: Encombrements des enveloppes en plastique moulées

**Ta slovenski standard je istoveten z: EN 61837-1:1999**

**ICS:**

31.140	Piezoelektrične in dielektrične naprave	Piezoelectric and dielectric devices
--------	---	--------------------------------------

**SIST EN 61837-1:2002****en**

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

EUROPEAN STANDARD  
 NORME EUROPÉENNE  
 EUROPÄISCHE NORM

**EN 61837-1**

June 1999

ICS 33.100.20

English version

**Surface mounted piezoelectric devices for frequency control and selection  
 Standard outlines and terminal lead connections  
 Part 1: Plastic moulded enclosure outlines  
 (IEC 61837-1:1999)**

Dispositifs piézoélectriques à montage  
 en surface pour la commande et le choix  
 de la fréquence - Encombrements  
 normalisés et connexions des sorties  
 Partie 1: Encombrements des  
 enveloppes en plastique moulées  
 (CEI 61837-1:1999)

Oberflächenmontierbare piezoelektrische  
 Bauteile zur Frequenzstabilisierung  
 und -Selektion  
 Norm-Gehäusemaße und Anschlüsse  
 Teil 1: Kunststoffgehäuse  
 (IEC 61837-1:1999)

[SIST EN 61837-1:2002](https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002)

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

This European Standard was approved by CENELEC on 1999-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

**CENELEC**

European Committee for Electrotechnical Standardization  
 Comité Européen de Normalisation Electrotechnique  
 Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

### Foreword

The text of document 49/431/FDIS, future edition 1 of IEC 61837-1, prepared by IEC TC 49, Piezoelectric and dielectric devices for frequency control and selection, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61837-1 on 1999-05-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2000-03-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2002-05-01

This Standard is to be used in conjunction with EN 61240:1997.

Annexes designated "normative" are part of the body of the standard.  
Annexes designated "informative" are given for information only.  
In this standard, annex ZA is normative and annex A is informative.  
Annex ZA has been added by CENELEC.

## iTeh STANDARD PREVIEW

Endorsement notice  
(standards.itih.ai)

The text of the International Standard IEC 61837-1:1999 was approved by CENELEC as a European Standard without any modification.

<https://standards.itih.ai/catalog/standards/sist/3fb70fd-d639-4854-9716->

In the official version, for annex A, Bibliography, the following notes have to be added for the standards indicated:

IEC 60368-2-2 NOTE: Harmonized as EN 60368-2-2:1999 (not modified).

IEC 60679-1 NOTE: Harmonized as EN 60679-1:1998 (not modified).

**Annex ZA (normative)****Normative references to international publications  
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61240	1994	Piezoelectric devices - Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection - General rules	EN 61240	1997

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

**NORME  
INTERNATIONALE  
INTERNATIONAL  
STANDARD**

**CEI  
IEC**

**61837-1**

Première édition  
First edition  
1999-05

---



---

**Dispositifs piézoélectriques à montage en surface  
pour la commande et le choix de la fréquence –  
Encombres normalisés  
et connexions des sorties –**

**Partie 1:  
Encombres des enveloppes  
en plastique moulées**

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-10441b785015/sist-en-61837-1-2002>

**Surface mounted piezoelectric devices  
for frequency control and selection –  
Standard outlines and terminal lead connections –**

**Part 1:  
Plastic moulded enclosure outlines**

© IEC 1999 Droits de reproduction réservés — Copyright - all rights reserved

Aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photo-copie et les microfilms, sans l'accord écrit de l'éditeur.

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission  
Telefax: +41 22 919 0300

3, rue de Varembe Geneva, Switzerland  
e-mail: inmail@iec.ch IEC web site <http://www.iec.ch>



Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

CODE PRIX  
PRICE CODE

U

Pour prix, voir catalogue en vigueur  
For price, see current catalogue

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE MOUNTED PIEZOELECTRIC DEVICES  
FOR FREQUENCY CONTROL AND SELECTION –  
STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –**

**Part 1: Plastic moulded enclosure outlines**

**FOREWORD**

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
- 5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61837-1 has been prepared by IEC technical committee 49: Piezoelectric and dielectric devices for frequency control and selection.

This International Standard shall be read in conjunction with IEC 61240.

The text of this standard is based on the following documents:

FDIS	Report on voting
49/431/FDIS	49/438/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Annex A is for information only.



IEC 61837 consists of the following parts under the general title: *Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections:*

Part 1 Plastic moulded enclosure outlines;

Part 2 Ceramic enclosure outlines <sup>1)</sup>;

Part 3 Metal enclosure outlines <sup>1)</sup>.

## iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

---

<sup>1)</sup> To be published.

## INTRODUCTION

The demand for surface-mounted devices (SMD) for frequency control and selection increases every year and IEC 61240, has been prepared in response to this demand. It has been necessary to prepare separate standards covering individual SMD outlines and terminal lead connections based on the general rules in IEC 61240.

After several discussions on the matter within TC 49, a proposal was prepared covering 61 types of enclosure designs, which has been accepted and issued as a committee draft. There is, however, a risk that these will not be widely used, as too many kinds of reformed types of leaded crystal units have been issued.

After considerable discussion on this matter at the TC 49 meeting in Rotterdam, it has been decided that the individual SMDs available should be separated into three parts depending on the material used to fabricate the enclosure. The three parts are:

- moulded plastic enclosures which are dealt with in this standard;
- ceramic enclosures which will be dealt with in IEC 61837-2; and
- metal enclosures which will be dealt with in IEC 61837-3.

## iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 61837-1:2002

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

# SURFACE MOUNTED PIEZOELECTRIC DEVICES FOR FREQUENCY CONTROL AND SELECTION – STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –

## Part 1: Plastic moulded enclosure outlines

### 1 Scope

This part of IEC 61837 deals with standard outlines and terminal lead connections as they apply to SMDs for frequency control and selection in plastic moulded enclosures and is based on IEC 61240.

### 2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 61837. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this part of IEC 61837 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 61240:1994, *Piezoelectric devices – Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection – General rules*

<https://standards.iteh.ai/catalog/standards/sist/3fb70fd-d639-4854-9716-fb441a8789d1/sist-en-61837-1-2002>

### 3 Configuration of enclosures

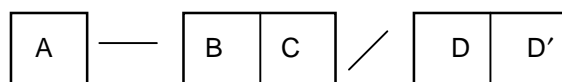
These enclosures are made of plastic moulded materials with the terminal leads based on Descriptive Designation System for Semiconductors – Devices Package.

The configuration symbols are shown as follows:

- DCC (dual chip carrier);
- QCC (quad chip carrier);
- SIP (single in-line package).

### 4 Designation of types

The designation of types is shown on the four parts as follows:



A: Configuration symbol of enclosures:

- DCC (dual chip carrier);
- QCC (quad chip carrier);
- SIP (single in-line package).

B: Structure of terminal leads:

- L: leaded type;
- J: folded leads type.

C: Number of terminal leads

D: Serial number of two figures

## 5 Plastic moulded enclosure dimensions

The dimensions in this standard apply to all the completed SMD-devices for frequency control and selection. Only those dimensions are given which meet the requirements of IEC 61240.

## 6 Lead connections

Recommendations for the lead connections of all completed SMD-devices for frequency control and selection are given in the following individual sheets. Lead connections shall always be given in the detail specification.

## 7 Plastic moulded enclosures

The following table sets out the designation of the plastic moulded enclosures as outlined in the ensuing specification sheets (standards.iteh.ai)

**Table 1 – Designation of plastic moulded enclosures**

No.	Type	Sheet No.	Description
1	DCC-J4/01	Sheet 1	Plastic, moulded, four folded leads SMD outline
2	DCC-J4/02	Sheet 2	Plastic, moulded, four folded leads SMD outline
3	DCC-J4/03	Sheet 3	Plastic, moulded, four folded leads SMD outline
4	DCC-J4/04	Sheet 4	Plastic, moulded, four folded leads SMD outline
5	DCC-J4/05	Sheet 5	Plastic, moulded, four folded leads SMD outline
6	DCC-J4/06	Sheet 6	Plastic, moulded, four folded leads SMD outline
7	DCC-J4/07	Sheet 7	Plastic, moulded, four folded leads SMD outline
8	DCC-J4/08	Sheet 8	Plastic, moulded, four folded leads SMD outline
9	SIP-L5/01	Sheet 9	Plastic, moulded, single in-line five leads SMD outline